

In the Claims

The claims have been amended as follows:

1 1.-10. (Canceled)

1 11. (Currently amended) An apparatus for removing contaminate particulate
2 matter from a contaminate particle containing integrated circuit semiconductor
3 substrate surface comprising:

4 a support for supporting a ~~an~~ integrated circuit semiconductor substrate
5 containing undesirable particulate matter on the surface of the substrate;

6 means for applying a sacrificial ~~material~~ coating of a curable polymer on the
7 surface of the substrate, which ~~material~~ curable polymer is to encapsulate
8 and suspend the undesirable particles therein;

9 means for fluidizing the curable polymer ~~material~~ if necessary;

10 energy forming means to dislodge at least some of the particulate matter from

11 the surface of the integrated circuit semiconductor substrate into the fluid

12 curable polymer sacrificial ~~material~~ coating such that the particulate matter

13 is partially or fully encapsulated and suspended within the sacrificial

14 curable polymer ~~material~~ coating forming a particulate matter containing

15 curable polymer sacrificial ~~material~~ coating; and

16 means for curing the fluidized particulate matter containing curable polymer

17 sacrificial coating to form a cured polymer strippable film; and

18 means for removing the particulate matter containing curable polymer
 19 sacrificial ~~material-coating~~ strippable film from the surface of the substrate as
 20 a strippable film providing a ~~cleaned~~ substrate surface having less
 21 particulate matter therein.

1 12. (Canceled)

1 13. (Currently amended) The apparatus of claim 11 wherein the sacrificial
 2 coating ~~material~~ curable polymer is a fluid.

1 14. (Original) The apparatus of claim 11 wherein the energy is sonic energy.

1 15. (Original) The apparatus of claim 11 wherein the energy means is thermal,
 2 centrifugal, magnetic or vibrational.

1 16. (Currently amended) The apparatus of claim 11 wherein the sacrificial
 2 coating curable polymer ~~material~~ is a liquid.

1 17.-20. (Canceled)

1 21. (Currently amended) A semiconductor electronic component made using
 2 the ~~method~~ apparatus of claim ~~[[1]]~~ 11.

1 22. (Currently amended) A semiconductor electronic component made using
2 the ~~method~~apparatus of claim [[4]]13.

1 23. (Currently amended) A semiconductor electronic component made using
2 the apparatus~~method~~ of claim [[5]]14.

1 24. (Currently amended) A semiconductor electronic component made using
2 the apparatus ~~method~~ of claim [[7]]15.

1 25. (Currently amended) A semiconductor electronic component made using
2 the apparatus~~method~~ of claim [[9]]16.

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